Programmable Timer

The MC14536B programmable timer is a 24–stage binary ripple counter with 16 stages selectable by a binary code. Provisions for an on–chip RC oscillator or an external clock are provided. An on–chip monostable circuit incorporating a pulse–type output has been included. By selecting the appropriate counter stage in conjunction with the appropriate input clock frequency, a variety of timing can be achieved.

Features

- 24 Flip–Flop Stages Will Count From 2⁰ to 2²⁴
- Last 16 Stages Selectable By Four-Bit Select Code
- 8-Bypass Input Allows Bypassing of First Eight Stages
- Set and Reset Inputs
- Clock Inhibit and Oscillator Inhibit Inputs
- On-Chip RC Oscillator Provisions
- On-Chip Monostable Output Provisions
- Clock Conditioning Circuit Permits Operation with Very Long Rise and Fall Times
- Test Mode Allows Fast Test Sequence
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–Power TTL Loads or One Low–Power Schottky TTL Load over the Rated Temperature Range
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

		66,	
Rating	Symbol	Value	Unit
DC Supply Voltage Range	V _{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V _{in} , V _{out}	-0.5 to V _{DD} + 0.5	V
Input or Output Current (DC or Transient) per Pin	I _{in} , I _{out}	±10	mA
Power Dissipation per Package (Note 1)	PD	500	mW
Ambient Temperature Range	T _A	-55 to +125	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Lead Temperature, (8–Second Soldering)	TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Packages: $-7.0 \text{ mW}^\circ\text{C}$ from 65°C to 125°C This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range V_{SS} \leq (V_{in} or V_{out}) \leq V_{DD}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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PIN ASSIGNMENT

SET [1●	16] V _{DD}
RESET [2	15] MONO-IN
IN 1 [3	14] OSC INH
OUT 1 [4	13] DECODE
OUT 2 [5	12] D
8-BYPASS	6	11] C
CLOCK INH	7	10] В
V _{SS} [8	9] A

MARKING DIAGRAMS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 12 of this data sheet.



Figure 1. Block Diagram

In ₁	Set	Reset	Clock Inh	OSC Inh	Out 1	Out 2	Decode Out
~	0	0	0	0	~	~	No Change
~	0	0	0	0	~	7	Advance to next state
Х	1	0	0	0	0	1	1
Х	0	1	0	0	0	1	0
х	0	0	1	0	-	-	No Change
х	0	0	0	1	0	1	No Change
0	0	0	0	Х	0	1	No Change
1	0	0	0		~	٦.	Advance to next state

FUNCTION TABLE

X = Don't Care

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				- 5	5°C		25°C		125°C		
Characteristi	c	Symbol	V _{DD} Vdc	Min	Мах	Min	Typ (Note 2)	Max	Min	Мах	Unit
Output Voltage $V_{in} = V_{DD}$ or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0 \text{ or } V_{DD}$	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95		Vdc
Input Voltage ($V_O = 4.5 \text{ or } 0.5 \text{ Vdc}$) ($V_O = 9.0 \text{ or } 1.0 \text{ Vdc}$) ($V_O = 13.5 \text{ or } 1.5 \text{ Vdc}$)	"0" Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11		Vdc
Output Drive Current ($V_{OH} = 2.5 \text{ Vdc}$) ($V_{OH} = 4.6 \text{ Vdc}$) ($V_{OH} = 9.5 \text{ Vdc}$) ($V_{OH} = 13.5 \text{ Vdc}$)	Source Pins 4 & 5	Іон	5.0 5.0 10 15	-1.2 -0.25 -0.62 -1.8	- - -	-1.0 -0.25 -0.5 -1.5	-1.7 -0.36 -0.9 -3.5		-0.7 -0.14 -0.35 -1.1		mAdc
$\begin{array}{l} (V_{OH} = 2.5 \; Vdc) \\ (V_{OH} = 4.6 \; Vdc) \\ (V_{OH} = 9.5 \; Vdc) \\ (V_{OH} = 13.5 \; Vdc) \end{array}$	Source Pin 13		5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	- - - -	-2.4 -0.51 -1.3 -3.4	-4.2 -0.88 -2.25 -8.8		-1.7 -0.36 -0.9 -2.4	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4		mAdc
Input Current		l _{in}	15	_	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	-	-	-	-	5.0	7.5	_	-	pF
Quiescent Current (Per I	Package)	I _{DD}	5.0 10 15	- - -	5.0 10 20	_ _ _	0.010 0.020 0.030	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (No (Dynamic plus Quiescen Per Package) ($C_L = 50 \text{ pF}$ on all output buffers switching)	it,	ΙŢ	5.0 10 15	$\begin{split} I_{T} &= (1.50 \; \mu\text{A/kHz}) \; \text{f} + I_{\text{DD}} \\ I_{T} &= (2.30 \; \mu\text{A/kHz}) \; \text{f} + I_{\text{DD}} \\ I_{T} &= (3.55 \; \mu\text{A/kHz}) \; \text{f} + I_{\text{DD}} \end{split}$					μAdc		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
3. The formulas given are for the typical characteristics only at 25°C.
4. To calculate total supply current at loads other than 50 pF:

 $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.003.

SWITCHING CHARACTERISTICS (Note 5) (C_L = 50 pF, T_A = 25° C)

Characteristic	Symbol	V _{DD}	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time (Pin 13) t_{TLH} , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ t_{TLH} , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ t_{TLH} , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15		100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q1, 8–Bypass (Pin 6) High t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 1715 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 617 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 425 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15		1800 650 450	3600 1300 1000	ns
Clock to Q1, 8–Bypass (Pin 6) Low t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 3715 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 1467 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 1075 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15		3.8 1.5 1.1	7.6 3.0 2.3	μs
Clock to Q16 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 6915 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 2967 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 2175 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15		7.0 3.0 2.2	14 6.0 4.5	μs
Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 1415 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 567 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 425 \text{ ns}$	t _{PHL}	5.0 10 15		1500 600 450	3000 1200 900	ns
Clock Pulse Width	t _{WH}	5.0 10 15	600 200 170	300 100 85	- - -	ns
Clock Pulse Frequency (50% Duty Cycle)	f _{cl}	5.0 10 15	_ _ _	1.2 3.0 5.0	0.4 1.5 2.0	MHz
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15		No Limit		_
Reset Pulse Width	t _{WH}	5.0 10 15	1000 400 300	500 200 150		ns

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

PIN DESCRIPTIONS

INPUTS

SET (Pin 1) – A high on Set asynchronously forces Decode Out to a high level. This is accomplished by setting an output conditioning latch to a high level while at the same time resetting the 24 flip–flop stages. After Set goes low (inactive), the occurrence of the first negative clock transition on IN_1 causes Decode Out to go low. The counter's flip–flop stages begin counting on the second negative clock transition of IN_1 . When Set is high, the on–chip RC oscillator is disabled. This allows for very low–power standby operation.

RESET (Pin 2) – A high on Reset asynchronously forces Decode Out to a low level; all 24 flip–flop stages are also reset to a low level. Like the Set input, Reset disables the on–chip RC oscillator for standby operation.

IN₁ (**Pin 3**) – The device's internal counters advance on the negative–going edge of this input. IN₁ may be used as an external clock input or used in conjunction with OUT_1 and OUT_2 to form an RC oscillator. When an external clock is used, both OUT_1 and OUT_2 may be left unconnected or used to drive 1 LSTTL or several CMOS loads.

8–BYPASS (Pin 6) – A high on this input causes the first 8 flip–flop stages to be bypassed. This device essentially becomes a 16–stage counter with all 16 stages selectable. Selection is accomplished by the A, B, C, and D inputs. (See the truth tables.)

CLOCK INHIBIT (Pin 7) – A high on this input disconnects the first counter stage from the clocking source. This holds the present count and inhibits further counting. However, the clocking source may continue to run. Therefore, when Clock Inhibit is brought low, no oscillator startup time is required. When Clock Inhibit is low, the counter will start counting on the occurrence of the first negative edge of the clocking source at IN_1 .

OSC INHIBIT (Pin 14) – A high level on this pin stops the RC oscillator which allows for very low–power standby operation. May also be used, in conjunction with an external clock, with essentially the same results as the Clock Inhibit input.

MONO–IN (Pin 15) – Used as the timing pin for the on–chip monostable multivibrator. If the Mono–In input is connected to V_{SS} , the monostable circuit is disabled, and Decode Out is directly connected to the selected Q output. The monostable circuit is enabled if a resistor is connected between Mono–In and V_{DD} . This resistor and the device's internal capacitance will determine the minimum output pulse widths. With the addition of an external capacitor to V_{SS} , the pulse width range may be extended. For reliable operation the resistor value should be limited to the range of 5 k Ω to 100 k Ω and the capacitor value should be limited to a maximum of 1000 pf. (See figures 4, 5, 6, and 11).

A, B, C, D (Pins 9, 10, 11, 12) – These inputs select the flip–flop stage to be connected to Decode Out. (See the truth tables.)

OUTPUTS

OUT₁, OUT₂ (Pin 4, 5) – Outputs used in conjunction with IN_1 to form an RC oscillator. These outputs are buffered and may be used for 2^0 frequency division of an external clock.

DECODE OUT (Pin 13) – Output function depends on configuration. When the monostable circuit is disabled, this output is a 50% duty cycle square wave during free run.

TEST MODE

The test mode configuration divides the 24 flip–flop stages into three 8–stage sections to facilitate a fast test sequence. The test mode is enabled when 8–Bypass, Set and Reset are at a high level. (See Figure 9.)

	In	put			Stage Selected
8–Bypass	D	С	В	Α	for Decode Out
0	0	0	0	0	9
0	0	0	0	1	10
0	0	0	1	0	11
0	0	0	1	1	12
0	0	1	0	0	13
0	0	1	0	1	14
0	0	1	1	0	15
0	0	1	1	1	16
0	1	0	0	0	17
0	1	0	0	1	18
0	1	0	1	0	19
0	1	0	1	1	20
0	1	1	0	0	21
0	1	1	0	1	22
0	1	1	1	0	23
0	1	1	1	1	24

TRUTH TABLES

	In	put			Stage Selected
8–Bypass	D	С	в	Α	for Decode Out
1	0	0	0	0	1
1	0	0	0	1	2
1	0	0	1	0	3
1	0	0	1	1	4
1	0	1	0	0	5
1	0	1	0	1	6
1	0	1	1	0	7
1	0	1	1	1	8
1	1	0	0	0	9
1	1	0	0	1	10
1	1	0	1	0	11
1	1	0	1	1	12
1	1	1	0	0	13
1	1	1	0	1	14
1	1	1	1	0	15
1	1	1	1	1	16

LOGIC DIAGRAM









FUNCTIONAL TEST SEQUENCE

Test function (Figure 9) has been included for the reduction of test time required to exercise all 24 counter stages. This test function divides the counter into three 8–stage sections and 255 counts are loaded in each of the 8–stage sections in parallel. All flip–flops are now at a "1". The counter is now returned to the normal 24–stages in series configuration. One more pulse is entered into In_1 which will cause the counter to ripple from an all "1" state to an all "0" state.



Figure 8. Switching Time Test Circuit and Waveforms

FUNCTIONAL TEST SEQUENCE

	Inputs			Outputs	Comments	
In ₁	Set	Reset	8–Bypass	Decade Out Q1 thru Q24	All 24 stages are in Reset mode.	
1	0	1	1	0		
1	1	1	1	0	Counter is in three 8 stage sections in parallel mode.	
0	1	1	1	0	First "1" to "0" transition of clock.	
1 0 - - -	1	1	1		255 "1" to "0" transitions are clocked in the counter.	
0	1	1	1	1	The 255 "1" to "0" transition.	
0	0	0	0	1	Counter converted back to 24 stages in series mode. Set and Reset must be connected together and simultaneously go from "1" to "0".	
1	0	0	0	1	In ₁ Switches to a "1".	
0	0	0	0	0	Counter Ripples from an all "1" state to an all "0" state.	



NOTE: When power is first applied to the device, DECODE OUT can be either at a high or low state. On the rising edge of a SET pulse the output goes high if initially at a low state. The output remains high if initially at a high state. Because CLOCK INH is held high, the clock source on the input pin has no effect on the output. Once CLOCK INH is taken low, the output goes low on the first negative clock transition. The output returns high depending on the 8–BYPASS, A, B, C, and D inputs, and the clock input period. A 2ⁿ frequency division (where n = the number of stages selected from the truth table) is obtainable at DECODE OUT. A 2⁰-divided output of IN₁ can be obtained at OUT₁ and OUT₂.

Figure 10. Time Interval Configuration Using an External Clock, Set, and Clock Inhibit Functions (Divide-by-2 Configured)



NOTE: When Power is first applied to the device with the RESET input going high, DECODE OUT initializes low. Bringing the RESET input low enables the chip's internal counters. After RESET goes low, the 2ⁿ/2 negative transition of the clock input causes DECODE OUT to go high. Since the MONO–IN input is being used, the output becomes monostable. The pulse width of the output is dependent on the external timing components. The second and all subsequent pulses occur at 2ⁿ x (the clock period) intervals where n = the number of stages selected from the truth table.

Figure 11. Time Interval Configuration Using an External Clock, Reset, and Output Monostable to Achieve a Pulse Output (Divide-by-4 Configured)

MC14536B



NOTE: This circuit is designed to use the on-chip oscillation function. The oscillator frequency is determined by the external R and C components. When power is first applied to the device, DECODE OUT initializes to a high state. Because this output is tied directly to the OSC INH input, the oscillator is disabled. This puts the device in a low-current standby condition. The rising edge of the RESET pulse will cause the output to go low. This in turn causes OSC INH to go low. However, while RESET is high, the oscillator is still disabled (i.e.: standby condition). After RESET goes low, the output remains low for 2ⁿ/2 of the oscillator's period. After the part times out, the output again goes high.

Figure 12. Time Interval Configuration Using On–Chip RC Oscillator and Reset Input to Initiate Time Interval (Divide–by–2 Configured)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14536BDWG	SOIC-16 WB (Pb-Free)	47 Units / Rail
NLV14536BDWG*	SOIC-16 WB (Pb-Free)	47 Units / Rail
MC14536BDWR2G	SOIC-16 WB (Pb-Free)	1000 / Tape & Reel
NLV14536BDWR2G*	SOIC-16 WB (Pb-Free)	1000 / Tape & Reel
NLV14536BDTR2G* (In Development)	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
MC14536BFELG	SOEIAJ–16 (Pb–Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
 *NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP

Capable.

PACKAGE DIMENSIONS





- NOTES:
 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION. MATERIAL CONDITION.

	MILLIMETERS					
DIM	MIN	MAX				
Α	2.35	2.65				
A1	0.10	0.25				
В	0.35	0.49				
С	0.23	0.32				
D	10.15	10.45				
Ε	7.40	7.60				
е	1.27	BSC				
н	10.05	10.55				
h	0.25	0.75				
L	0.50	0.90				
q	0 °	7 °				

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS



G

-T- SEATING PLANE

D

NOTES:

DIMENSIONING AND TOLERANCING PER ANSI

 1. DIMENSIONING AND CONTROLLING DIMENSION: MILLIMETER.
 2. CONTROLLING DIMENSION: MILLIMETER.
 CONTROLLING ADDES NOT INCLUDE MOLD
 CONTROLLING ADDES NOT INCLUDE MOLD
 CONTROLLING ADDES NOT INCLUDE MOLD 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

A. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

DIMENSION K DOES NOT INCLUDE DAMBAR 5. PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. 5. TERMINAL NUMBERS ARE SHOWN FOR

6. 6. TEHMINAL NUMBER OF ALL STOCK REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT

7. DIMENSION A 7 DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
κ	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	6.40 BSC		BSC	
М	0 °	8 °	0 °	8 °	

SOLDERING FOOTPRINT*

DETAIL E

Н



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966 ISSUE A

Q₁



0.10 (0.004)



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE
 MEASURED AT THE PARTING LINE. MOLD FLASH
 OR PROTRUSIONS SHALL NOT EXCEED 0.15
 (0 006) DEG SIDE
- (0.006) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- TELMINUC ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.10	0.20	0.007	0.011	
D	9.90	10.50	0.390	0.413	
E	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
Μ	0 °	10 °	0 °	10 °	
Q ₁	0.70	0.90	0.028	0.035	
Z		0.78		0.031	

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PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

← b 0.13 (0.005) (M)

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